

[54] SEMI-CONDUCTOR MOUNTING SUBSTRATE

4,677,526 6/1987 Muehling et al. 357/70 X
4,698,663 10/1987 Sugimoto et al. 174/52.4 X

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FOREIGN PATENT DOCUMENTS

0048945 3/1983 Japan 357/74
0150353 7/1986 Japan 357/74
0271863 12/1986 Japan 357/70
0035653 2/1987 Japan .

[*] Notice: The portion of the term of this patent subsequent to May 14, 2005 has been disclaimed.

OTHER PUBLICATIONS

Disc Controller Pictured on p. 190, *Electronic Design*, 10-16-86.
NCR IC Package Pictured on p. 7, *Electronic Design*, 10-16-86.
CMOS Chip Pictured on p. 131, *Electronics*, 8-7-86.
Fujitsu Substrate Pictured on p. 7, *Electronics*, 2-24-86.

[**] Term: 14 Years

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Assistant Examiner—Joel Sincavage
Attorney, Agent, or Firm—Lorusso & Loud

[21] Appl. No.: 140,433

[22] Filed: Jan. 4, 1988

[30] Foreign Application Priority Data

Jul. 4, 1987 [JP] Japan 62-27274

[52] U.S. Cl. D13/182

[58] Field of Search D13/12, 20, 99;
361/401, 403, 404, 405; 357/70, 72, 74, 80;
174/52.4; 437/209

[57] CLAIM

The ornamental design for a semi-conductor mounting substrate, as shown.

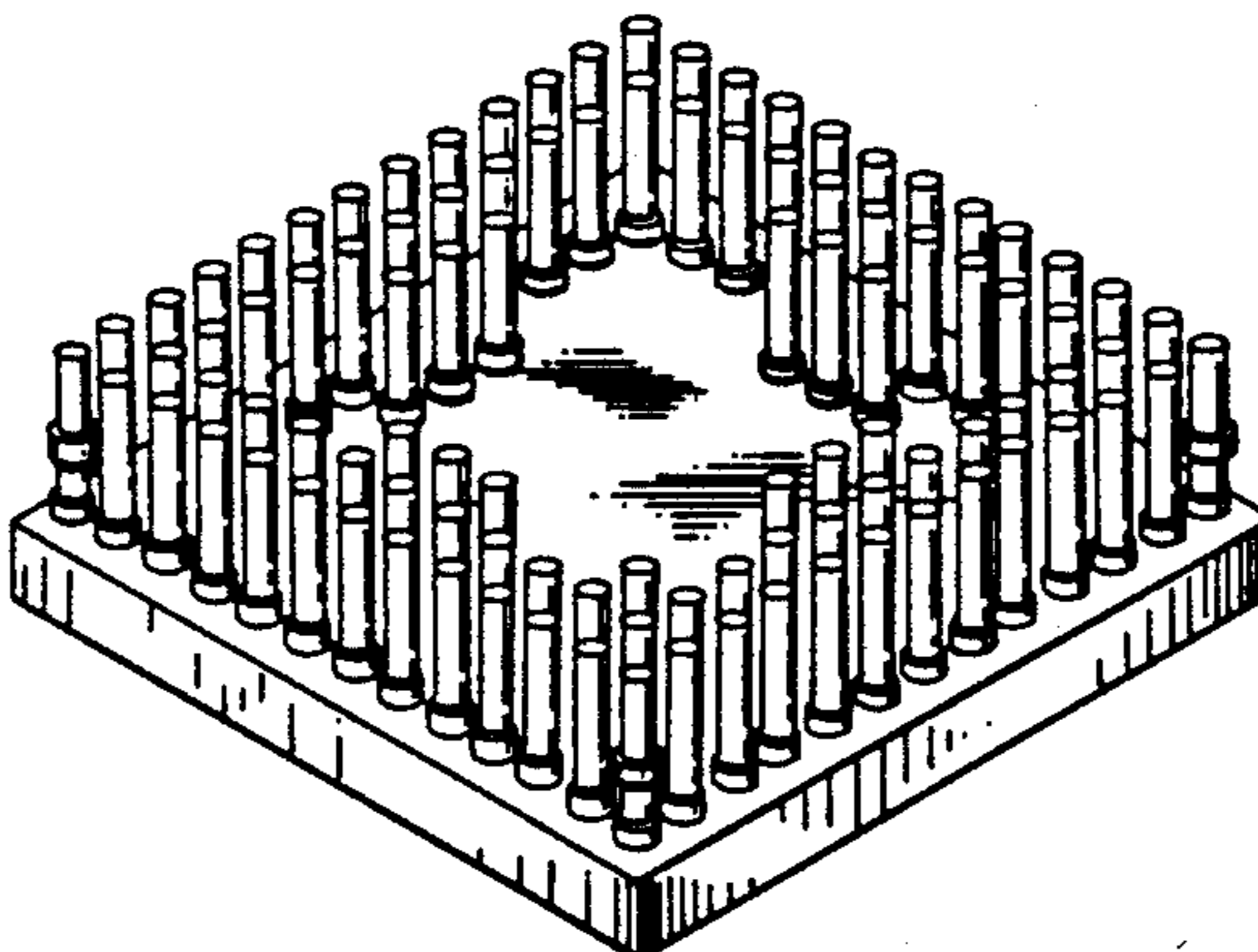
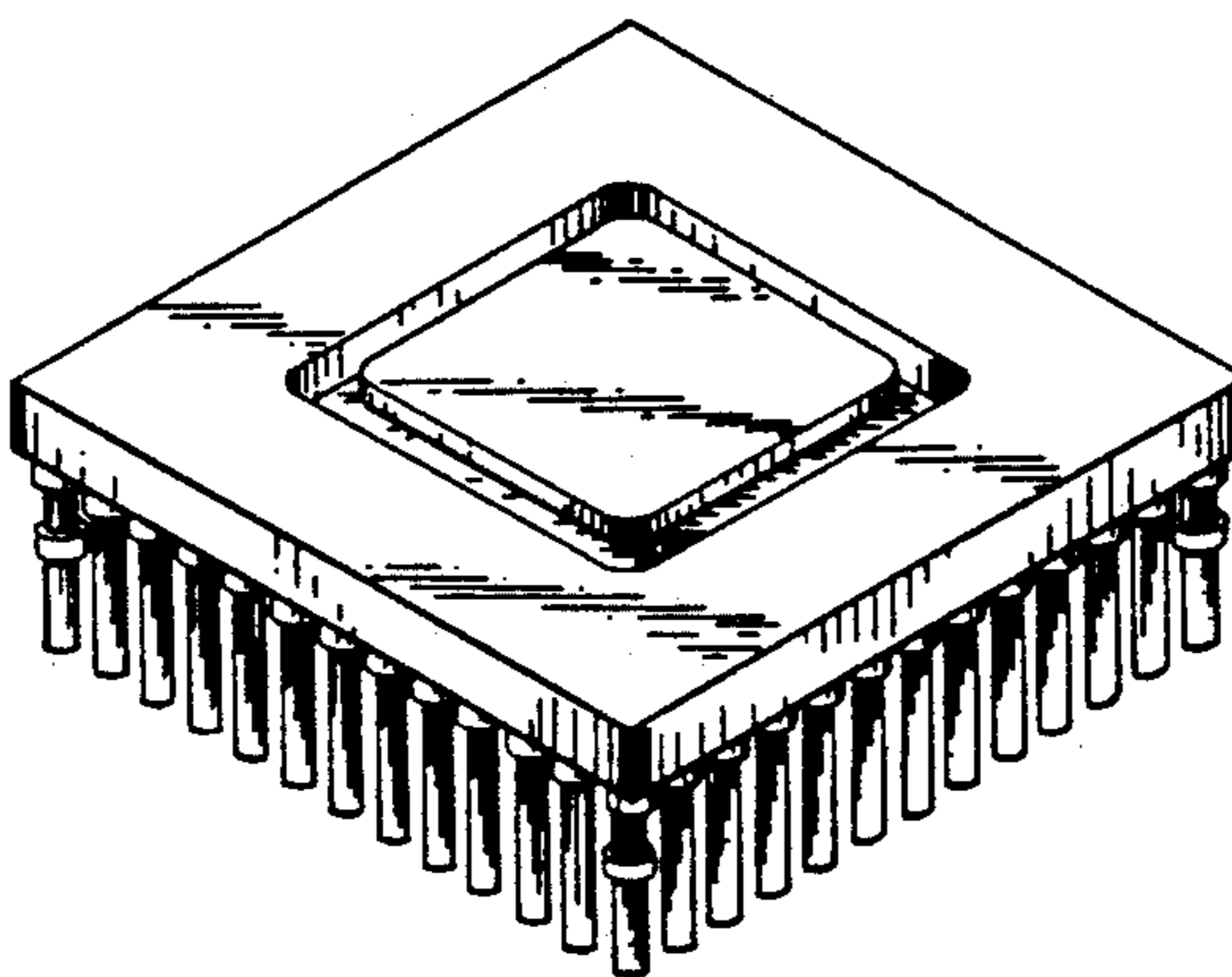
[56] References Cited

U.S. PATENT DOCUMENTS

4,288,841 9/1981 Gogal .
4,338,621 7/1982 Braun 357/80 X
4,437,141 3/1984 Prokop .
4,458,291 7/1984 Yanagisawa et al. 174/52.4 X
4,513,355 4/1985 Shroeder et al. .

DESCRIPTION

FIG. 1 is a top perspective view of a semi-conductor mounting substrate showing our new design; FIG. 2 is a bottom perspective view thereof; FIG. 3 is a right side elevational view thereof; FIG. 4 is a left side elevational view thereof; FIG. 5 is a rear elevational view thereof; and FIG. 6 is a front elevational view thereof.



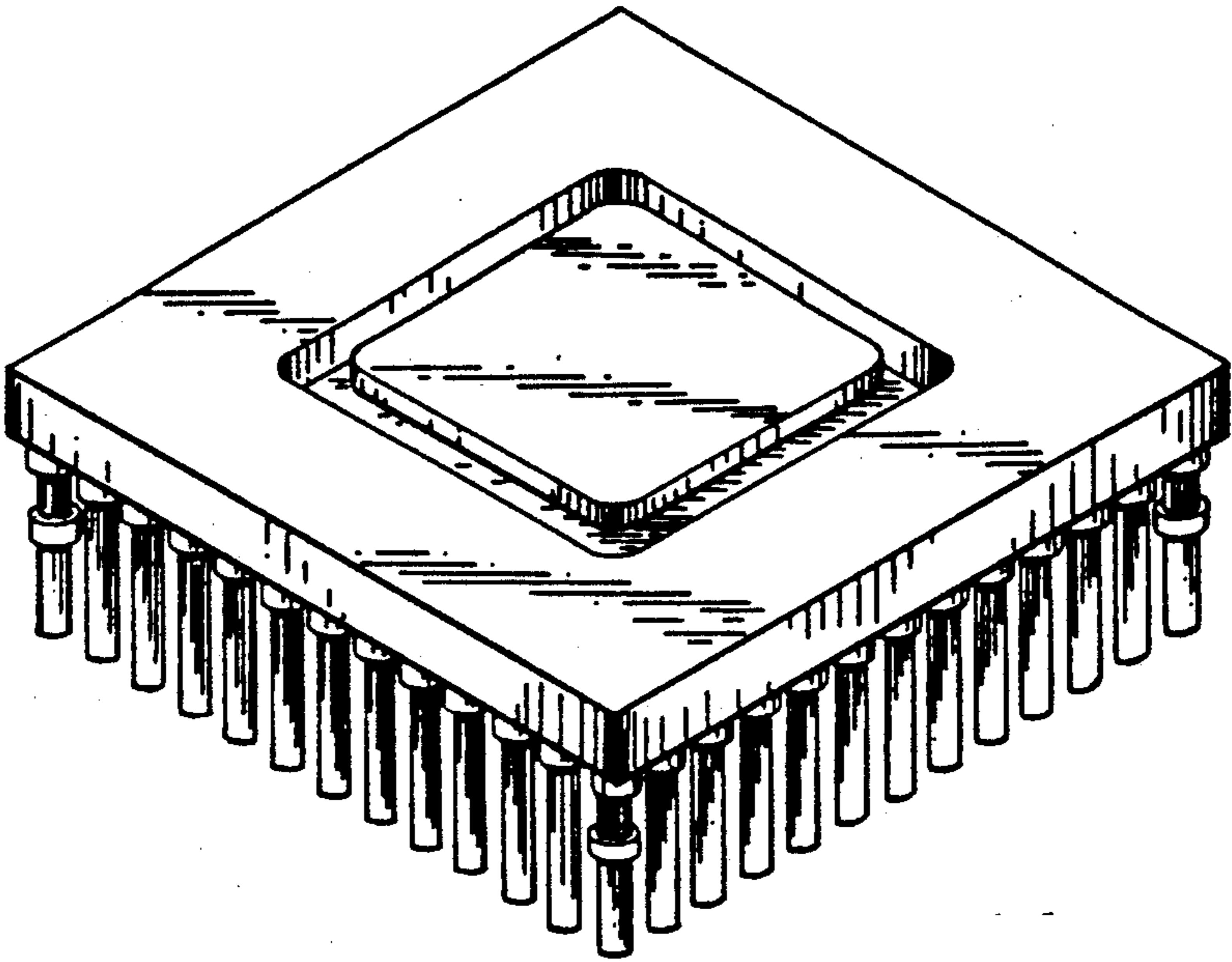


FIG. 1

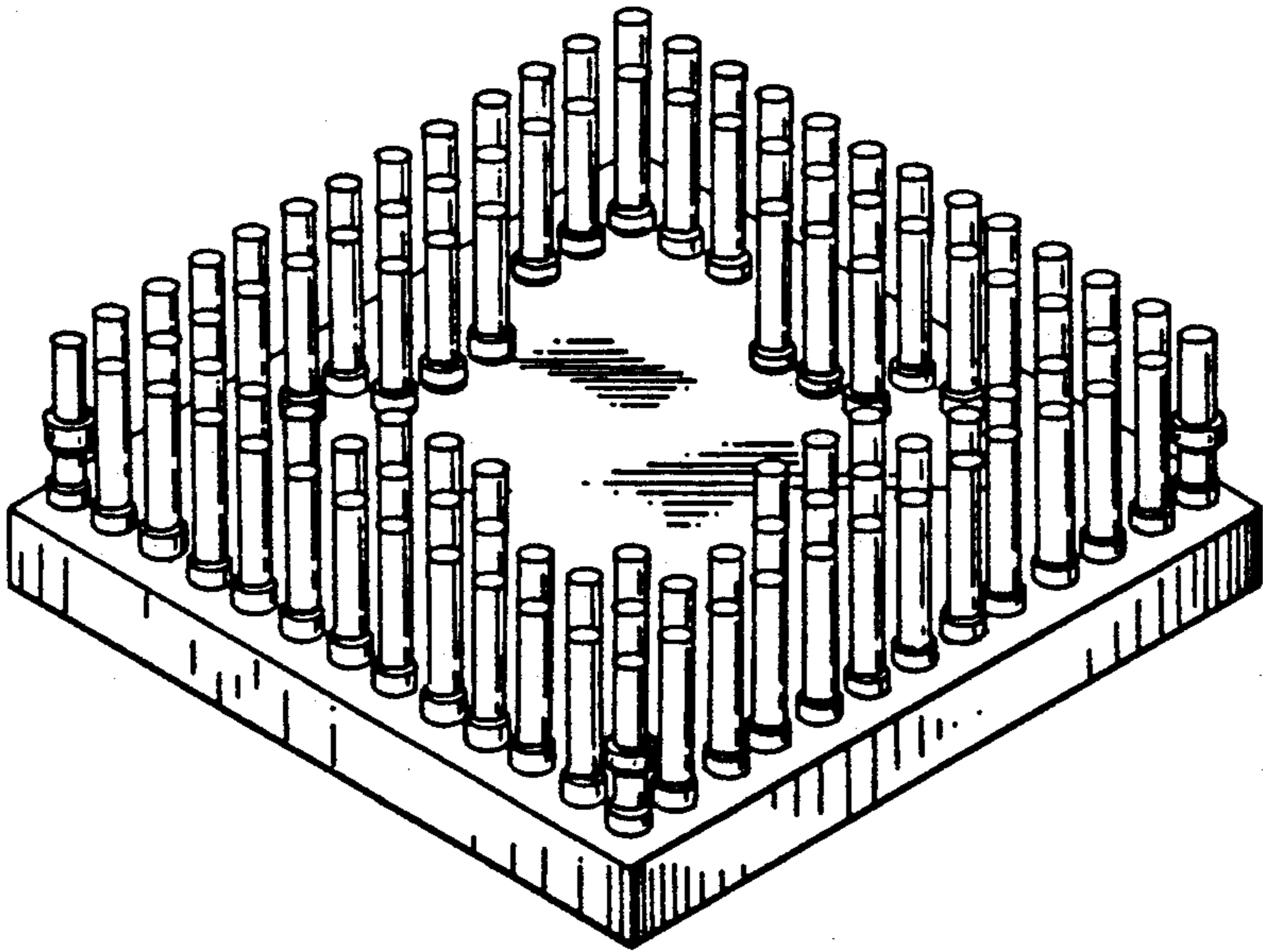


FIG. 2

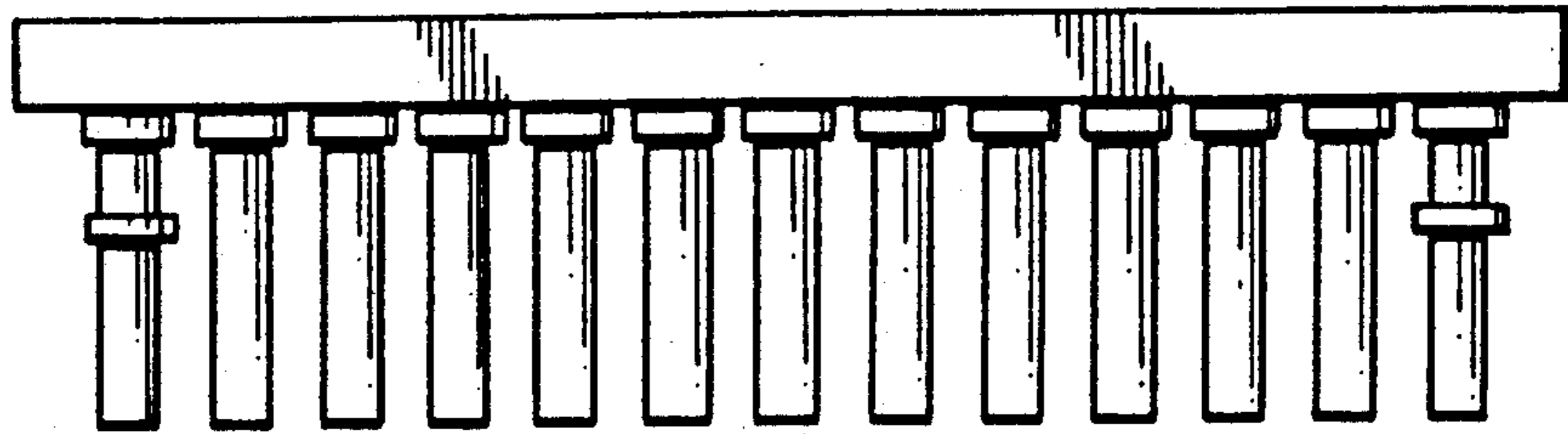


FIG. 3

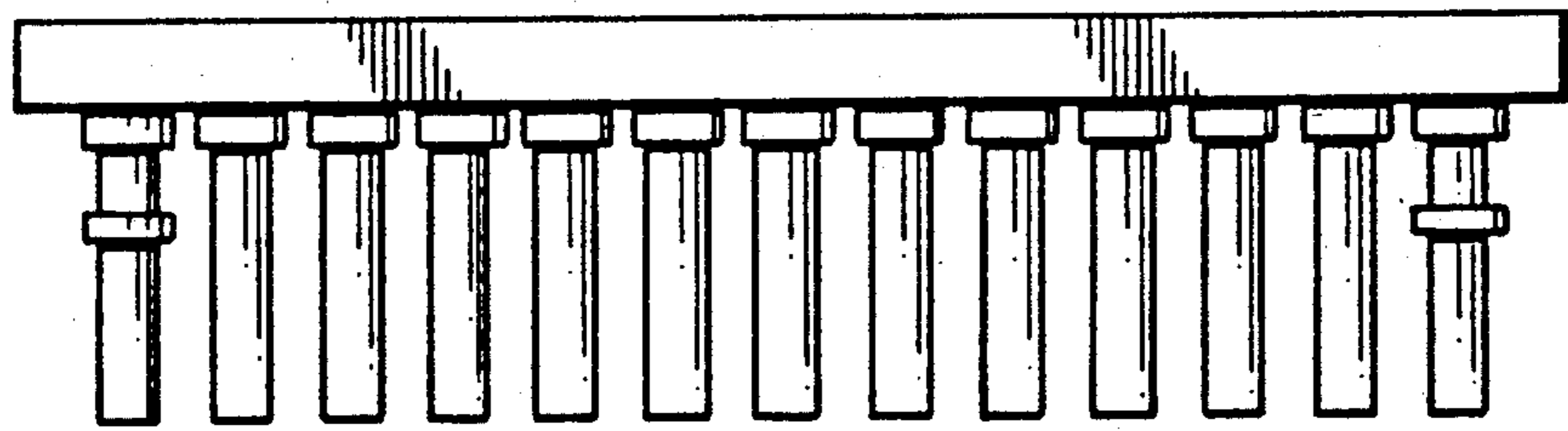


FIG. 4

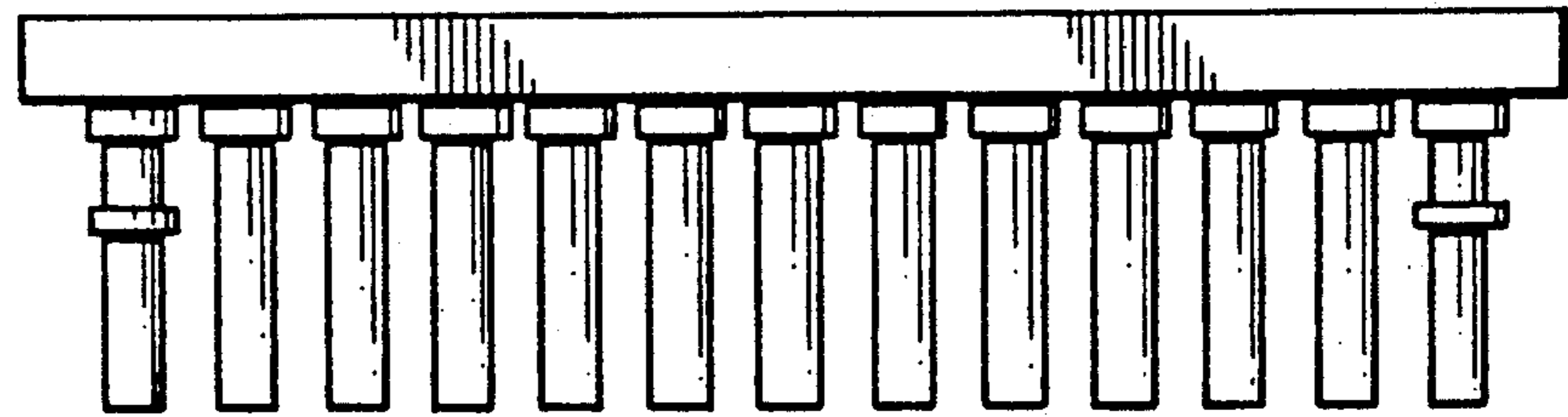


FIG. 5

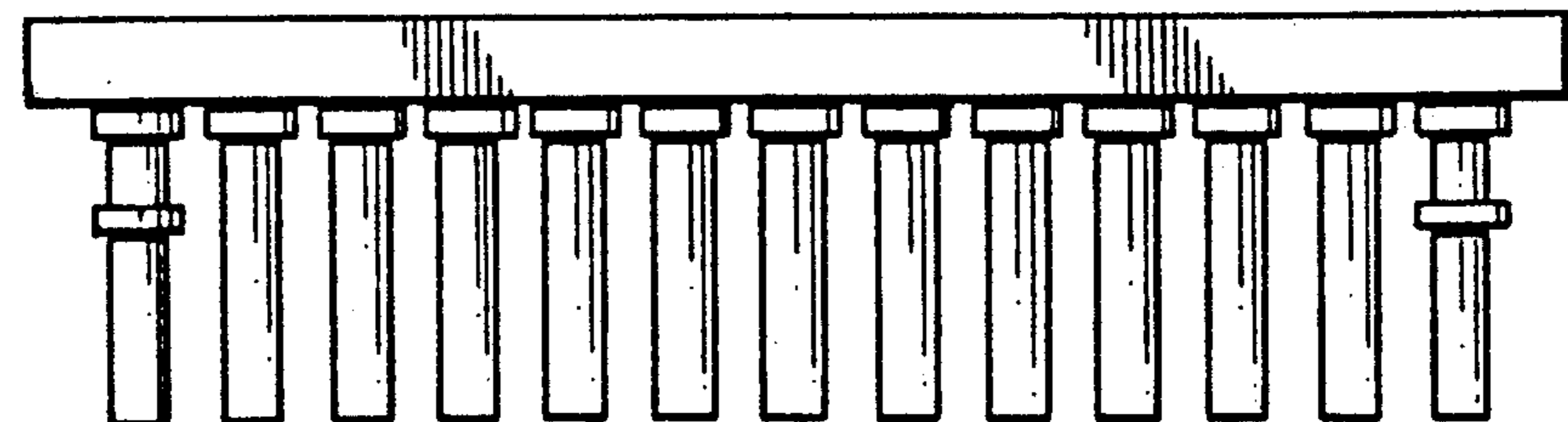


FIG. 6